

Product Data Sheet

TACFlux® 483

Introduction

TACFlux® 483 is a no-clean flux formulated for SnPb solders. **TACFlux® 483** provides excellent wetting (Air or Nitrogen atmosphere) to many surfaces, including Ni. Its many uses include rework/repair and SMT component attach (including BGA and Flip-Chip). A minimum reflow temperature of approximately 200°C (dependent on reflow profile and method) is recommended to sufficiently drive off all volatiles for consideration in no-clean applications.

Properties

J-STD-004 (IPC-TM-650)	
Test	Result
Flux Type Classification	ROL1
Flux Induced Corrosion (Copper Mirror)	Pass
Presence of Halide: Silver Chromate Fluoride Spot Test Cl Equivalent	Pass Pass ~0.067%
Post Reflow Flux Residue (ICA Test)	~48%
Typical Thixotropic Index (SSF)	~-0.86
SIR	Pass
Bellcore Electromigration Acid Value	Pass ~98
Viscosity (Brookfield)	~500kcps
Specific Gravity	~1.1g/ml
Tack	~270g

Additional Test Results:	
Appearance	Light Yellow-Amber
Maximum Reflow Temperature	300°C
Reflow Atmosphere	Nitrogen or Air
Shelf Life	1 year
Storage Condition	Stored @ 0-30°C (tip down for syringe/cartridge)

All information is for reference only. Not to be used as incoming product specifications.

Packaging

TACFlux® 483 is available in 10cc and 30cc syringes or 100g jars, however other packaging can be provided to meet specific requirements.

Cleaning

TACFlux® 483 is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner.

Reflow

Peak reflow temperature should be <300°C in an air or nitrogen atmosphere.

Storage

TACFlux® 483 syringes and cartridges should be stored tip down at 0-30°C. **TACFlux® 483** should be thawed for 4 hours at room temperature before using.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon and paste. Indium Corporation Technical Support engineers provide Rapid Response to all technical inquiries.

Material Safety Data Sheets

The MSDS for this product can be found online at <http://www.indium.com/techlibrary/msds.php>



This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products

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